Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	("20020023715").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/02 20:28
S2	23	(("3855024") or ("6562695") or ("6503361") or ("6431949") or ("6332832") or ("6077385") or ("6621264") or ("5514245") or ("5559428") or ("5644221") or ("5659492") or ("5660672") or ("5663637") or ("5731697") or ("6575948") or ("6579148") or ("6579148") or ("6579148") or ("6579148") or ("6582282") or ("6602724")).PN.	USPAT; USOCR	OR	OFF	2004/11/09 18:41
S3	15	((("3855024") or ("6562695") or ("6503361") or ("6431949") or ("6332832") or ("6077385") or ("6621264") or ("6292708") or ("6251789") or ("5514245") or ("5559428") or ("5660672") or ("5663637") or ("5676587") or ("5731697") or ("5770948") or ("6555466") or ("6558229") or ("6579148") or ("6582282") or ("6602724")).PN.) and water	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 18:42
S4	4851	((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR ~	OFF	2004/11/10 13:38
S5	53	(((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and polish\$3 same (rins\$4 with water) and (metal adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/09 19:38
S6	37	(((((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and polish\$3 same (rins\$4 with water) and (metal adj layer)) and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 17:36

S7	2	("6251789").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 12:26
S8	4	(("6251789") or ("6621264")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 12:26
S9	4851	((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/10 13:41
S10	253	(((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and (polish\$3 with load)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 15:48
S11	14	((((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and polish\$\$3 same (rins\$\$4 with water) and (metal adj layer)) and (@rlad<="20001001" or @ad<="20001001") and load	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 17:12
S12	2	(((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and ((polish\$3 with load) same (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 15:19
S13	21	((polish\$3 with load) same (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 15:20
S14	2	((pressing adj load) with (tungsten or copper or (conductive adj layer)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 15:41
S15	0	((pressing adj load) with (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 15:42

S16	1	((pressing adj load) same (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 15:43
S17	251	(polish\$3 same load same ((metal adj layer) or tungsten or copper))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2004/11/10 15:50
S18	103	((polish\$3 same load same ((metal adj layer) or tungsten or copper))) and titanium	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 17:12
S19	103	((polish\$3 same load same ((metal adj layer) or tungsten or copper))) and titanium	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 17:12
S20	62	(((polish\$3 same load same ((metal adj layer) or tungsten or copper))) and titanium) and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 17:41
S21	122	load same CMP same change	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 17:41
S22	91	(load same CMP same change) and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/10 17:47
S23	2	("6292708").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/15 10:11
S24	39	((((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and polish\$3 same (rins\$4 with water) and (metal adj layer)) and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 17:20

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S25	281	(((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and (polish\$3 with load)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 17:20
S26	15	((((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and polish\$3 same (rins\$4 with water) and (metal adj layer)) and (@rlad<="20001001" or @ad<="20001001") and load	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 17:20
S27	3	(((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and ((polish\$3 with load) same (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2005/05/10 17:20
S28	23	((polish\$3 with load) same (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 17:20
S29	2	`((pressing adj load) with (tungsten or copper or (conductive adj layer)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/05/10 17:20
S30	2	((pressing adj load) same (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 17:20
S31	274	(polish\$3 same load same ((metal adj layer) or tungsten or copper))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 17:20
S32	66	(((polish\$3 same load same ((metal adj layer) or tungsten or copper))) and titanium) and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2005/05/10 17:20
S33	92	(load same CMP same change) and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 17:20

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S34	13	(S24 or S25 or S26 or S27 or S28 or S29 or S30 or S31 or S32 or S33) and @pd>="20041110" and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 22:37
S35	5706	((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/02 22:55
S36	0	S35 and ((polish\$3 with (first metal layer)) same (detect\$3 with (end point))) and (clean\$3 with (surface or platen)) and (polish\$3 with (second metal layer)) and ((measur\$3 with (second metal layer)) same optic\$3) and ((clean\$3 with (substrate or wafer or workpiece)) same dry\$3) and ((detect\$4 or measur\$4) same dry same (film thickness))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 21:34
S37	0	((polish\$3 with (first metal layer)) same (detect\$3 with (end point))) and (clean\$3 with (surface or platen)) and (polish\$3 with (second metal layer)) and ((measur\$3 with (second metal layer)) same optic\$3) and ((clean\$3 with (substrate or wafer or workpiece)) same dry\$3) and ((detect\$4 or measur\$4) same dry same (film thickness))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 21:06
538		S35 and ((polish\$3 same (first metal layer)) same (detect\$3 same (end point))) and (polish\$3 same (second metal layer) same dect\$3 same (end point)) and ((clean\$3 with (substrate or wafer or workpiece)) same dry\$3) and ((detect\$4 or measur\$4) same (film thickness))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 21:47
S39	0	((polish\$3 same (first metal layer)) same (detect\$3 same (end point))) and (polish\$3 same (second metal layer) same dect\$3 same (end point)) and ((clean\$3 with (substrate or wafer or workpiece)) same dry\$3) and ((detect\$4 or measur\$4) same (film thickness))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 21:53

S40	0	((polish\$3 same (first metal layer))	HC DCDHD	ADI	ON	2005/10/02 21:54
540	U	same (detect\$3 same (end point))) and (polish\$3 same (second metal layer) same dect\$3 same (end point)) and ((clean\$3 with (substrate or wafer or workpiece)) same dry\$3) and ((detect\$4 or measur\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 21:54
S41	3	(polish\$3 and (first metal layer) and (detect\$3 with (end point)) and (second metal layer) and (clean\$3 with (substrate or wafer or workpiece)) same dry\$3) and (detect\$4 or measur\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 22:08
S42	39	((((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and polish\$3 same (rins\$4 with water) and (metal adj layer)) and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:39
S43	295	(((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and (polish\$3 with load)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:39
S44	15	(((((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and polish\$3 same (rins\$4 with water) and (metal adj layer)) and (@rlad<="20001001" or @ad<="20001001") and load	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:39
S45	4	(((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and ((polish\$3 with load) same (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:39
S46	26	((polish\$3 with load) same (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR ,	ON	2005/10/02 22:39
S47	2	((pressing adj load) with (tungsten or copper or (conductive adj layer)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:39
S48	2	((pressing adj load) same (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:39

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S49	281	(polish\$3 same load same ((metal adj layer) or tungsten or copper))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:39
S50	68	(((polish\$3 same load same ((metal adj layer) or tungsten or copper))) and titanium) and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:39
S51	92	(load same CMP same change) and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:57
S52	428	(S42 or S43 or S44 or S45 or S46 or S47 or S48 or S49 or S50 or S51) and @pd>="2000510" and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 22:40
S53	4	(S42 or S43 or S44 or S45 or S46 or S47 or S48 or S49 or S50 or S51) and @pd>="20050510" and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ.	ON	2006/04/24 11:45
S54	361	S35 and (measure same ((film or layer) with thickness))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 22:56
S55	154	(S54) and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 23:34
S56	86	S55 and cmp	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2005/10/02 23:35
S57	20	(in-situ with measur\$4) and ((in-line or post) with measur\$4) and feedback	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON .	2006/04/20 16:11

S58	9	(in-situ with measur\$4) and	US-PGPUB;	ADJ	ON	2006/04/24 12:27
	,	((in-line or post) with measur\$4) and feedback and CMP	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB		Olv	2000/07/27 12.2/
S59	134	(in-situ and measur\$4) and (in-line or post) and feedback and CMP and (@rlad<="20010525" or @ad<="20010525")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/20 18:04
S60	74	in-situ and measur\$4 and (in-line or (stand alone)) and feedback and CMP and (@rlad<="20010525" or @ad<="20010525")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/20 18:10
S61	6055	((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/24 15:44
S62	40	((((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and polish\$3 same (rins\$4 with water) and (metal adj layer)) and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 11:46
S63	319	(((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and (polish\$3 with load)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 11:46
S64	16	((((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and polish\$3 same (rins\$4 with water) and (metal adj layer)) and (@rlad<="20001001" or @ad<="20001001") and load	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/04/24 11:46
S65	5	(((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and ((polish\$3 with load) same (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 18:19
S66	. 28	((polish\$3 with load) same (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 11:46

S67	2	((pressing adj load) with (tungsten or copper or (conductive adj layer)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 11:46
S68	2	((pressing adj load) same (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 11:46
S69	308	(polish\$3 same load same ((metal adj layer) or tungsten or copper))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 11:46
S70	68	(((polish\$3 same load same ((metal adj layer) or tungsten or copper))) and titanium) and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 11:46
S71	94	(load same CMP same change) and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 11:46
S72	385	S61 and (measure same ((film or layer) with thickness))	US-PGPUB; USPAT; USOCR;	ADJ	ON	2006/04/24 11:46
			EPO; JPO; DERWENT; IBM_TDB			φ.
S73	154	(S72) and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 11:46
S74	86	S73 and cmp	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 11:46
S75	4	(S62 or S63 or S64 or S65 or S66 or S67 or S68 or S69 or S70 or S71 or S74) and @pd>="20051002" and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/24 12:08

S76	4	(polish\$3 and (first metal layer) and (detect\$3 with (end point)) and (second metal layer) and (clean\$3 with (substrate or wafer or workpiece)) same dry\$3) and (detect\$4 or measur\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/24 12:08
S77	1	(S76) and @pd>="20051002" and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/24 16:03
S78		(S74) and @pd>="20051002" and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/24 12:22
S79	17	(in-situ with measur\$4) and ((in-line or station or chamber) with measur\$4) and feedback and CMP	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/24 14:40
S80	2	("6984168").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/24 14:40
S81	2	S61 and load\$3 and unload\$3 and (polishing (section or chamber)) and (clean\$3 same dry\$3) and ((film thickness) with measur\$5 with (chamber or device))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/24 16:00
S82	2	S61 and load\$3 and unload\$3 and (polishing (section or chamber)) and (clean\$3 same dry\$3) and ((film thickness) with measur\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON .	2006/04/24 16:01
S83	4	S61 and load\$3 and unload\$3 and (polishing (section or chamber)) and (clean\$3 same dry\$3) and ((thickness) with measur\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ΑDÌ	ON	2006/04/24 16:02

S84	52	load\$3 and unload\$3 and (polishing (section or chamber)) and (clean\$3 same dry\$3) and ((thickness) with measur\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/24 16:02
S85	26	(S84) and (@rlad<="20010525" or @ad<="20010525")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/04/25 18:20
S88	134	(((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89, 85,86)).CCLS.) and (clean\$\$3 same dry\$\$3) and (@rlad<="2000525" or @ad<="20000525")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/26 11:21
S89	735	CMP and (clean\$3 same dry\$3) and (@rlad<="2000525" or @ad<="20000525")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/26 11:22
S90	841	CMP and (clean\$3 same dry\$3) and (@rlad<="19990525" or @ad<="19990525")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/26 11:24
S91	468	CMP and (clean\$3 same dry\$3) and (@rlad<="19980525" or @ad<="19980525")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/26 11:27
S92	303	CMP and (clean\$3 same dry\$3 same (chamber or section or machine)) and (@rlad<="19990525" or @ad<="19990525")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/26 11:29
S93	90	CMP and (clean\$3 same dry\$3 same (chamber or section or machine)) and (measur\$ same (film or layer or thickness)) and (@rlad<="19990525" or @ad<="19990525")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/26 11:32
S94	16	("20020115397" "5486129" "5605488" "5716258" "5851140" "5916015" "5916016" "5964653" "5980367" "5993302" "6024630" "6036587" "6056632" "6062133" "6068549" "6290577").PN. OR ("6984168"). URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/04/26 16:21

S95	4	(("6409576") or ("6984168")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/26 16:26
S96	2	("6984168").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/26 16:26